				(42114).
L Number	Hits	<u> </u>	DB	Time stamp
1	14	342/\$9.ccls. and (ltcc low-temperature adj	USPAT;	2004/02/21 21:44
		(cofired co-fired) adj ceramic)	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	2	342/\$9.ccls. and (ltcc low-temperature adj	USPAT;	2004/02/21 22:36
		(cofired co-fired) adj ceramic).ti,ab,clm.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
3	643	(333/26).CCLS.	IBM_TDB USPAT	2004/02/21 22:37
4	3	863030.ap.	USPAT;	2004/02/21 22:37
-		00000.up.	US-PGPUB;]
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/01 00 46
5	2	LTCC.ti,ab,clm. and 342/\$9.ccls.	USPAT;	2004/02/21 22:46
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
6	3	mmic near12 transceiver.ti,ab,clm. and	USPAT;	2004/02/21 22:47
		455/\$9.ccls.	US-PGPUB;	
			EPO; JPO;	
·			DERWENT;	
7	3	863030.ap.	IBM_TDB USPAT;	2004/02/21 22:49
,		000000.ap.	US-PGPUB;	2001,02,21 22.13
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/10/05 15 14
_	0	mmic.ti. and transceiver.clm.	USPAT;	2003/10/27 17:11
			US-PGPUB; EPO; JPO;	
	:		DERWENT;	
			IBM TDB	
-	15	mmic.ti. and transceiver	USPAT;	2002/09/14 14:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_ !	1	mmic.ti. and transceiver and (tuned or	USPAT;	2002/09/14 14:13
	_	tuning)	US-PGPUB;	2002/05/14 14:15
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	2002/20/24 21 25
-	0	mmic.ti. and transceiver.ti,ab,clm. and	USPAT;	2002/09/14 14:15
		(tuned or tuning).ti,ab.clm.	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	(mmic or microwave adj monolithic).ti. and	USPAT;	2002/09/14 14:44
İ		transceiver.ti,ab,clm. and (tuned or	US-PGPUB;	
		tuning).ti,ab.clm.	EPO; JPO;	
			DERWENT; IBM TDB	
_	0	(mmic or microwave adj monolithic).ti. and	USPAT;	2002/09/14 14:44
		transceiver.ti,ab,clm. and 438/\$6.ccls.	US-PGPUB;	, ~_,,,,,
			EPO; JPO;	
ļ			DERWENT;	
		/	IBM_TDB	2002/00/14 11 11
-	20	(mmic or microwave adj monolithic).ti. and 438/\$6.ccls.	USPAT; US-PGPUB;	2002/09/14 14:44
		130/40.00T2.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	370	integrated adj circuit adj board.ti.	USPĀT;	2002/09/17 12:07
			US-PGPUB;	
			EPO; JPO;	
ł			DERWENT; IBM TDB	
	<u></u>		100 100	

-	7	integrated adj circuit adj board.ti. and integrated adj circuit adj board.clm.	USPAT; US-PGPUB;	2002/09/17 12:08
			EPO; JPO; DERWENT; IBM TDB	
_	634	(455/73).CCLS.	USPAT; US-PGPUB;	2002/10/20 16:25
			EPO; JPO; DERWENT;	
_	147	(257/277).CCLS.	IBM_TDB USPAT;	2002/10/20 16:25
			US-PGPUB; EPO; JPO; DERWENT;	
_	551	(257/728).CCLS.	IBM_TDB USPAT;	2002/10/20 16:26
			US-PGPUB; EPO; JPO;	
	1978	(mmic or monolithic adj microwave adj	DERWENT; IBM_TDB USPAT;	2002/10/20 16:26
	1378	integrated adj circuit).ti,ab,clm.	US-PGPUB; EPO; JPO;	2002/10/20 10:20
			DERWENT; IBM_TDB	
- .	1325	((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)	USPAT; US-PGPUB; EPO; JPO;	2002/10/20 16:27
			DERWENT; IBM TDB	
-	70	integrated adj circuit).ti,ab,clm.) and	USPAT; US-PGPUB;	2002/10/20 16:27
		(((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))	EPO; JPO; DERWENT; IBM TDB	
_	3233	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or	USPAT; US-PGPUB;	2002/10/20 16:27
		(((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))	EPO; JPO; DERWENT;	
_	221	(((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or	IBM_TDB USPAT; US-PGPUB;	2002/10/20 16:28
		(((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))) and	EPO; JPO; DERWENT;	
_	4	1 , , , , , , , , , , , , , , , , , , ,	IBM_TDB USPAT;	2002/10/20 16:29
		integrated adj circuit).ti,ab,clm.) or (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))) and	US-PGPUB; EPO; JPO; DERWENT;	
		transceiver.ti,ab,clm.) and transfer adj	IBM_TDB	
_	2	("5545924").PN.	USPAT; US-PGPUB; EPO; JPO;	2002/10/20 17:13
			DERWENT; IBM TDB	
-	2	("6124636").PN.	USPAT; US-PGPUB;	2002/10/20 17:14
			EPO; JPO; DERWENT; IBM TDB	
_	13	"5423080"	USPAT; US-PGPUB;	2002/10/20 17:14
			EPO; JPO; DERWENT;	
_	. 2	("5423080").PN.	IBM_TDB USPAT; US-PGPUB;	2002/10/20 17:14
		,	EPO; JPO; DERWENT;	
<u></u>			IBM TDB	

_	18	(US-5423080-\$ or US-6124636-\$ or US-6424074-\$ or US-6124765-\$ or US-6278337-\$ or US-6278159-\$ or	USPAT; US-PGPUB; DERWENT	2002/10/20 17:34
	1	US-6424074-\$ or US-6124765-\$ or US-6278337-\$ or US-6278159-\$ or US-5545924-\$ or US-6268779-\$ or US-6073484-\$ or US-6441449-\$ or US-6201728-\$ or US-6257058-\$).did. or (US-20010001224-\$).did. or (EP-712534-\$ or EP-504020-\$ or JP-11214578-\$ or	USPAT; US-PGPUB; DERWENT	2002/10/20 17:35
_	2724	WO-200075762-\$ or WO-200223674-\$).did.) and transfer adj tape mmic or monolithic adj microwave adj intergated adj circuit and transfer adj	USPAT; US-PGPUB;	2002/10/20 17:35
_	5	integrated adj circuit) and transfer adj	DERWENT USPAT; US-PGPUB;	2002/10/20 17:36
_	19	US-5423080-\$ or US-6124636-\$ or US-5545924-\$ or US-6257058-\$ or US-6278159-\$ or US-6278337-\$ or US-6201728-\$ or US-6124765-\$ or US-6424074-\$ or US-6073484-\$ or US-6268779-\$).did. or (US-20010001224-\$).did. or (EP-504020-\$ or	DERWENT USPAT; US-PGPUB; DERWENT	2002/10/20 19:33
	8	JP-11214578-\$ or EP-712534-\$ or WO-200223674-\$ or WO-200075762-\$).did. ((US-5451818-\$ or US-6441449-\$ or US-5423080-\$ or US-6124636-\$ or US-5545924-\$ or US-6257058-\$ or US-6278159-\$ or US-6278337-\$ or US-6201728-\$ or US-6124765-\$ or US-6424074-\$ or US-6073484-\$ or US-6268779-\$).did. or (US-20010001224-\$).did. or (EP-504020-\$ or JP-11214578-\$ or EP-712534-\$ or WO-200223674-\$ or WO-200075762-\$).did.) and thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:05
	18		USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/20 20:07
-	0	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil near12 base)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/20 20:08
_	17	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/20 20:12
-	25	cte near4 gaas	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/20 20:50
_	2	("5451818").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:50

_	2	("5451818").PN.	USPAT;	2002/10/21 07:56
			US-PGPUB;	
1			EPO; JPO;	ţ
			DERWENT;	
	0	("solder near3 MMIC adj chip").PN.	USPAT;	2002/10/21 07:56
-		(Solder Hears Marc adj Chip): IN:	US-PGPUB;	2002/10/21 07:30
	•		EPO; JPO;	
			DERWENT;	
			IBM TDB	1
	7	solder near3 MMIC adj chip	USPAT;	2002/10/21 08:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	silver adj epoxy near6 MMIC	USPAT;	2002/10/21 08:13
			US-PGPUB;	
ļ			EPO; JPO;	
			DERWENT; IBM TDB	
_	3	silver adj epoxy near12 chip and	USPAT;	2002/10/21 08:14
		MMIC.ti, ab, clm.	US-PGPUB;	2002/10/21 00:14
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
-	5	silver adj epoxy near12 (die or chip) and	USPAT;	2002/10/21 08:15
		(monolithic adj microwave or	US-PGPUB;	
		MMIC).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	6	,	USPAT;	2002/10/21 08:21
		(monolithic adj microwave or MMIC)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	16	solder near4 preform and MMIC	USPAT;	2002/10/21 08:21
_	10	Solder hear4 preform and mmic	US-PGPUB;	2002/10/21 08:21
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	13	solder near4 preform and MMIC.ti,ab,clm.	USPAT;	2002/10/21 08:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	(radio-frequency or radio adj frequency or	USPAT;	2002/10/21 08:34
		rf) adj (lid or cover) near15 (MMIC or	US-PGPUB;	
		monolithic adj microwave)	EPO; JPO; DERWENT;	
			IBM TDB	
_	1	(radio-frequency or radio adj frequency or	USPAT;	2002/10/21 08:34
		rf or kovar) adj (lid or cover) near15	US-PGPUB;	,, 00.01
		(MMIC or monolithic adj microwave)	EPO; JPO;	
		,	DERWENT;	
			IBM_TDB	
_	2	'	USPAT;	2002/10/21 09:03
		rf or kovar) near4 (lid or cover) near15	US-PGPUB;	
1		(MMIC or monolithic adj microwave)	EPO; JPO;	
			DERWENT;	
<u> </u>	158	isolation near? /wia or through_hele or	IBM_TDB USPAT;	2002/10/21 09:05
	138	isolation near3 (via or through-hole or through adj hole) and (chip or	USPAT; US-PGPUB;	
		die).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	20	isolation adj (via or through-hole or	USPAT;	2002/10/21 09:05
	İ	through adj hole) and (chip or	US-PGPUB;	
		die).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
				_

				·
_	5		USPAT;	2002/10/21 09:07
		through adj hole) and (chip or	US-PGPUB;	
		die).ti,ab,clm. and (mmic or monolithic	EPO; JPO; DERWENT;	
		adj microwave)	IBM TDB	
_	6	(insulation or isolation or insulating or	USPAT;	2002/10/21 09:11
	Ĭ	isolating) adj (via or through-hole or	US-PGPUB;	
		through adj hole) and (chip or	EPO; JPO;	
		die).ti,ab,clm. and (mmic or monolithic	DERWENT;	
		adj microwave)	IBM_TDB	
_	47	isolation adj via.ti,ab,clm.	USPAT;	2002/10/21 09:12
			US-PGPUB;	
	:		EPO; JPO;	
			DERWENT;	
	1	isolation adj via.ti,ab,clm. and mmic	IBM_TDB USPAT;	2002/10/21 09:12
_		isolation adj via.ti,ab,tim. and munit	US-PGPUB;	2002/10/21 09:12
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
_	6	isolation adj via.ti,ab,clm. and (chip or	USPAT;	2002/10/21 09:17
	1	die)	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
!	_		IBM_TDB	2002/12/21 22 12
-	1	(isolation adj via or isolation adj	USPAT;	2002/10/21 09:18
		trench).ti,ab,clm. and (chip or die) and	US-PGPUB;	
		mmic	EPO; JPO; DERWENT;	
			IBM TDB	
_	3097	mmic and sti or isolation adj trench	USPAT;	2002/10/21 09:19
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	(isolation adj trench or sti) same mmic	USPAT;	2002/10/21 09:19
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	112	(isolation adj trench or sti) same chip	USPAT;	2002/10/21 09:20
		and (integrated adj circuit or	US-PGPUB;	
		ic).ti,ab,clm.	EPO; JPO;	_
			DERWENT;	
			IBM_TDB	
_	4	(isolation adj trench or sti) and mmic	USPAT;	2002/10/21 09:31
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	12	epoxy near1 silver and integrated adj	USPAT;	2002/10/21 10:00
		circuit and mmic	US-PGPUB;	
			EPO; JPO;	
			DERWENT;]
	_	/#5451010#\ 7\\	IBM_TDB	0000/10/01 10 01
-	2	("5451818").PN.	USPAT;	2002/10/21 10:01
			US-PGPUB; EPO; JPO;	
]			DERWENT;	
			IBM TDB	
-	2	("5319329").PN.	USPAT;	2002/10/21 10:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		(#E020C0E#\ D\)	IBM_TDB	2002/10/21 12 21
-	2	("5239685").PN.	USPAT;	2002/10/21 10:01
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
<u></u>	I	<u></u>	<u> </u>	·

			<u></u>	· · · · · · · · · · · · · · · · · · ·
-	2	("5406122").PN.	USPAT;	2002/10/21 10:02
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	("5049978").PN.	USPAT;	2002/10/21 10:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	2	("6426686").PN.	USPAT;	2002/10/21 10:02
	[1	US-PGPUB;	2000, 20, 22 20.02
			EPO; JPO;	
l.			DERWENT;	
			IBM_TDB	0000/00/00 11 00
-	0	("863030.ap.").PN.	USPAT;	2003/03/27 11:23
	:		US-PGPUB; EPO; JPO;	
			DERWENT;	
İ			IBM TDB	
_	3	863030.ap.	USPAT;	2003/03/27 11:46
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		/HEAE1010H) DV	IBM TDB	2002/02/22 12 24
-	2	("5451818").PN.	USPAT; US-PGPUB;	2003/03/27 12:04
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	("MMIC.ti,ab,clm. and thick adj film adj	USPĀT;	2003/03/27 12:04
		capacitor").PN.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1	MMTC ti ah alm and thick adi film adi	IBM_TDB USPAT;	2003/03/27 12:11
-		MMIC.ti,ab,clm. and thick adj film adj capacitor	US-PGPUB;	2003/03/2/ 12:11
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	MMIC.ti, ab, clm. and air near2 (insulation	USPAT;	2003/03/27 12:12
		or isolation or isolate or insulate)	US-PGPUB;	
		near12 (transmit or transmission) near12 (receive or receiver)	EPO; JPO; DERWENT;	,
		/Teretae Of Teretaer/	IBM TDB	
_	О	MMIC.ti,ab,clm. and (spacing or air) near2	USPAT;	2003/03/27 12:13
		(insulation or isolation or isolate or	US-PGPUB;	
		insulate) near12 (transmit or	EPO; JPO;	
		transmission) near12 (receive or receiver)	DERWENT;	
		MMTO (IBM_TDB	2002/02/07 10 15
-	0	MMIC same (spacing or air) near12 (insulation or isolation or isolate or	USPAT;	2003/03/27 12:15
		insulation or isolation or isolate or insulate) nearl2 (transmit or	US-PGPUB; EPO; JPO;	
		transmission) near12 (receive or receiver)	DERWENT;	
			IBM TDB	
 	13	(spacing or air) near12 (insulation or	USPĀT;	2003/03/27 12:16
		isolation or isolate or insulate) near12	US-PGPUB;	
		(transmit or transmission) near12 (receive	EPO; JPO;	
		or receiver)	DERWENT; IBM TDB	
_	o	(spacing or air) near12 (insulation or	USPAT;	2003/03/27 12:17
		isolation or isolate or insulate) near12	US-PGPUB;	2000,00,21 12.11
		(transmit or transmission) near12 (receive	EPO; JPO;	
		or receiver) and (257/\$6.ccls. or	DERWENT;	
		438/\$6.ccls.)	IBM_TDB	
-	2	(spacing or air) near12 (insulation or	USPAT;	2003/03/27 12:19
		isolation or isolate or insulate) near12	US-PGPUB;	
		(transmit or transmission) near12 (receive or receiver) and (257/\$6.ccls. or	EPO; JPO; DERWENT;	
		438/\$6.ccls. or 455/\$6.ccls.)	IBM TDB	
<u></u>		200/40.0019. OT 400/40.0019./	1211 121	L

_	13		USPAT;	2003/03/27 17:05
		isolation or isolate or insulate) near12	US-PGPUB;	
		(transmit or transmission) near12 (receive	EPO; JPO; DERWENT;	
		or receiver)	IBM TDB	
	2	488721.ap.	USPAT;	2003/03/27 13:12
			US-PGPUB;	
;			EPO; JPO;	
			DERWENT;	•
			IBM_TDB	
-	37	LTCC and MMIC	USPAT;	2003/03/27 13:13
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	LTCC near12 transfer adj tape and MMIC	USPAT;	2003/03/27 13:13
!			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/02/27 12:10
_	4	LTCC and transfer adj tape and MMIC	USPAT;	2003/03/27 13:18
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	4	LTCC and transfer adj tape and (monolithic	USPĀT;	2004/02/21 22:42
	1	adj microwave adj integrated adj circuit	US-PGPUB;	
		or MMIC)	EPO; JPO;	
			DERWENT;	
	7	(low adj temperature adj co-fired adj	IBM_TDB USPAT;	2003/03/27 14:43
_	′	ceramic or LTCC) and transfer adj tape and	US-PGPUB;	2003/03/27 14.43
		(monolithic adj microwave adj integrated	EPO; JPO;	
		adj circuit or MMIC)	DERWENT;	
			IBM_TDB	
-	170	· · ·	USPAT;	2003/03/27 14:44
		resistor	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	73	MMIC.ti,ab,clm. and capacitor same	USPAT;	2003/03/27 14:44
		resistor.ti,ab,clm.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	MMTC hi ob ole and sees the sees	IBM_TDB	2002/02/27 14:45
_	5	MMIC.ti,ab,clm. and capacitor same	USPAT; US-PGPUB;	2003/03/27 14:45
		resistor.ti,ab,clm. and transceiver.ti,ab,clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	1427	((257/277) or (257/728) or (455/73)).CCLS.	USPAT;	2003/03/27 17:07
	:		US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	81	(((257/277) or (257/728) or	USPAT;	2003/03/27 17:10
		(455/73)).CCLS.) and (mmic or monolithic	US-PGPUB;	
		adj microwave adj integrated adj	EPO; JPO;	[
		circuit).ti,ab,clm.	DERWENT;	
			IBM_TDB	
-	8		USPAT;	2003/03/27 17:10
		(455/73)).CCLS.) and (mmic or monolithic adj microwave adj integrated adj	US-PGPUB; EPO; JPO;	
		circuit).ti,ab,clm. and transceiver	DERWENT;	
		orroard, or any orm, and cranscerver	IBM TDB	
_	505	(mem or microelectromechanical).ti.	USPAT;	2003/03/27 19:38
			US-PGPUB;	
			DERWENT	0000/05/55
_	160	,	USPAT	2003/03/27 19:42
-	14	((mem or microelectromechanical).ti.) and 257/\$6.ccls.	USPAT	2003/03/27 19:42
	I .	201/40.0012.	1	1

	4	(mem or microelectromechanical).ti. and	USPAT	2003/03/27 19:42
_	80	pixel mmic.ti.	USPAT	2003/10/26 15:24
_	2	863030.ap.	USPAT	2003/10/26 15:24
-	3	1	USPAT;	2003/10/26 15:25
] _	3	863030.ap.	US-PGPUB	2003/10/20 13.23
_	353	(257/664).CCLS.	USPAT;	2003/10/26 15:30
_	23	(mmic monolithic adj microwave adj	US-PGPUB USPAT;	2003/10/26 15:53
		intergated adj circuit).ti,ab,clm. and transceiver.ti,ab,clm.	US-PGPUB	
_	3	863030.ap.	USPAT; US-PGPUB	2003/10/26 15:53
_	1	"5111199".PN.	USPAT	2003/10/26 15:56
! _	1	"5588041".PN.	USPAT	2003/10/26 15:57
_	1	"5422783".PN.	USPAT	2003/10/26 15:57
_	1	"6064341".PN.	USPAT	2003/10/26 15:58
_	1	"6157545".PN.	USPAT	2003/10/26 15:59
	1	"5512901".PN.	USPAT	2003/10/26 15:59
	10		USPAT;	2003/10/26 16:04
-	10	US-6594479-\$ or US-6522868-\$ or	US-PGPUB	2003/10/20 10:04
		1	05-FGF05	
		US-6442374-\$).did. or (US-20030169134-\$ or		
		US-20020171141-\$ or US-20020086655-\$ or		
	20	US-20020055349-\$ or US-20020030250-\$).did.	HGDAm.	2003/10/26 16:22
-	39	(US-5423080-\$ or US-6441449-\$ or	USPAT;	2003/10/20 10:22
		US-5406122-\$ or US-6424074-\$ or	US-PGPUB;	
[US-6278159-\$ or US-6278337-\$ or	DERWENT	
		US-6257058-\$ or US-6268779-\$ or		
1		US-6124765-\$ or US-6201728-\$ or		
		US-6073484-\$ or US-5451818-\$ or		
		US-6124636-\$ or US-5545924-\$ or		
		US-6498551-\$ or US-6507110-\$ or		
		US-6522868-\$ or US-6476463-\$ or		
		US-6442374-\$ or US-6072991-\$ or		
		US-6627992-\$ or US-6594479-\$ or		
		US-5111199-\$ or US-5422783-\$ or		1
		US-5239685-\$ or US-5319329-\$).did. or		
		(US-20010001224-\$ or US-20020030250-\$ or]
		US-20030169134-\$ or US-20020086655-\$ or		
		US-20020055349-\$ or US-20020171141-\$).did.		
		or (EP-504020-\$ or US-5451818-\$ or		
		US-5239685-\$ or WO-200075762-\$ or		
		WO-200223674-\$ or JP-11214578-\$ or		
		EP-712534-\$).did.	Habre	0000/10/06 16 00
_		("5451818").PN.	USPAT	2003/10/26 16:22
_	203	`	USPAT	2003/10/27 08:58
		(multi-layered multi-layer multilayer		
		multilayered) near12 ceramic	110000	0000/10/07 00 00
-	161	(controlled adj firing co-fired) near6	USPAT	2003/10/27 09:22
		(multi-layered multi-layer multilayer		
		multilayered) near6 ceramic	7,000	0000/10/05 10 05
-	30	(controlled adj firing co-fired) near6	USPAT	2003/10/27 10:36
	1	(multi-layered multi-layer multilayer		
	_	multilayered) near6 ceramic.ti,ab,clm.		0000/10/07
_	8	green adj tape and (mmic monolithic adj	USPAT;	2003/10/27 11:43
		microwave adj intergated adj	US-PGPUB;	
		circuit).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_] 14		USPAT;	2003/10/27 13:28
		mmic) and (green adj tape co-fired	US-PGPUB;	
		co-firing controlled adj firing) near12	EPO; JPO;	
		ceramic	DERWENT;	[
			IBM_TDB	
-	60	millimeter and transceiver and (monolithic	USPAT;	2003/10/27 13:33
		mmic) and ceramic	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

-	1	millimeter and transceiver and (monolithic	USPAT;	2003/10/27 13:36
		mmic) and ceramic and 455/73.ccls.	US-PGPUB; EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
_	286	455/\$9.ccls. and (monolithic adj microwave	USPĀT;	2003/10/27 13:37
		mmic)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	73	455/\$9.ccls. and (monolithic adj microwave	USPAT;	2003/10/27 13:37
	, ,	mmic) and transceiver	US-PGPUB;	2003/10/2/ 13:31
			EPO; JPO;	
			DERWENT;	
	750	455 470	IBM_TDB	2002/10/27 12:27
-	758	455/73.ccls.	USPAT; US-PGPUB;	2003/10/27 13:37
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	13	,	USPAT;	2003/10/27 13:41
		microwave adj monolithic)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	412	(455/73).CCLS.	USPAT;	2003/10/27 14:10
			US-PGPUB	
_	514	343/700	USPAT;	2003/10/27 14:11
	1.5		US-PGPUB	0003/10/07 10:00
_	15	transfer adj tape and (millimeter adj wave mm adj wave monolotic adj microwave)	USPAT; US-PGPUB;	2003/10/27 18:39
		Muli adj wave monorotic adj mittowave)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	863030.ap.	USPAT;	2003/10/27 18:25
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	416	(333/247).CCLS.	USPAT;	2003/10/27 18:41
			US-PGPUB	
-	5	((333/247).CCLS.) and (transfer adj tape	USPAT;	2003/10/27 20:21
	1	ceramic) and transceiver and (mmic monolithic adj microwave millimeter adj	US-PGPUB	
		wave)		
_	11	watanabe.in. and (microwave millimeter)	USPAT;	2003/10/27 20:22
		and package and "chips"	US-PGPUB	
-	11	watanabe.in. and (microwave millimeter)	USPAT;	2003/10/27 20:22
		and package and "chips"	US-PGPUB;	
]		EPO; JPO; DERWENT;	
	1		IBM TDB	
-	3	863030.ap.	USPAT;	2003/10/28 09:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	28	green adj tape lttt ltcc low adj	USPAT;	2003/10/28 09:13
		temperature transfer adj tape low adj	US-PGPUB;	
		temperature adj (cofired co adj fired) adj	EPO; JPO;	
		ceramic) near6 high adj temperature	DERWENT;	
_	3272	(green add tano 1+++ 1+ac love add	IBM_TDB USPAT;	2003/10/28 09:13
	3212	(green adj tape lttt ltcc low adj temperature transfer adj tape low adj	US-PGPUB;	2003/10/20 03:13
	<u> </u>	temperature chansies and cape low and temperature adj (cofired co adj fired) adj	EPO; JPO;	
		ceramic) and GHz.	DERWENT;	
			IBM_TDB	
-	184	(green adj tape lttt ltcc low adj	USPAT;	2003/10/28 09:13
		temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj	US-PGPUB; EPO; JPO;	
		ceramic) and "20" near2 GHz	DERWENT;	
			IBM TDB	

-	32	temperature transfer adj tape low adj	USPAT; US-PGPUB;	2003/10/28 09:14
		temperature adj (cofired co adj fired) adj ceramic) and "20" near2 GHz and mmic	EPO; JPO; DERWENT; IBM TDB	;
_	9	(green adj tape lttt ltcc low adj temperature transfer adj tape low adj	USPAT; US-PGPUB;	2003/10/28 09:20
		temperature adj (cofired co adj fired) adj	EPO; JPO;	·
		ceramic) and "20" near2 GHz and mmic.ti,ab,clm.	DERWENT; IBM_TDB	
-	666	(333/26).CCLS.	USPAT; US-PGPUB	2003/10/28 09:20
_	1	((333/26).CCLS.) and (green adj tape lttt ltcc low adj temperature transfer adj tape	USPAT; US-PGPUB;	2003/10/28 09:21
		low adj temperature adj (cofired co adj fired) adj ceramic) and ("20" "30") near2	EPO; JPO; DERWENT;	
	9	GHz and mmic.ti,ab,clm. ((green adj tape lttt ltcc low adj	IBM_TDB USPAT;	2003/10/28 09:44
		temperature transfer adj tape low adj	US-PGPUB;	2003/10/20 03.11
		temperature adj (cofired co adj fired) adj ceramic) and "20" near2 GHz and	EPO; JPO; DERWENT;	
		mmic.ti,ab,clm.) and (green adj tape lttt ltcc low adj temperature transfer adj tape	IBM_TDB	
		low adj temperature adj (cofired co adj fired) adj ceramic) and ("20" "30") near2		
_	0	GHz and mmic.ti,ab,clm. multiple adj MMIC adj chips near6 single	USPAT;	2003/10/28 09:45
		adj substrate	US-PGPUB; EPO; JPO;	
			DERWENT; IBM TDB	
-	0	(plurality multiple) adj MMIC adj chips near6 single adj substrate	USPAT; US-PGPUB;	2003/10/28 09:45
			EPO; JPO; DERWENT;	
_	44	(plurality multiple) adj "chips" near6	IBM_TDB USPAT;	2003/10/28 09:45
		single adj substrate	US-PGPUB; EPO; JPO;	2003/10/20 03.13
			DERWENT; IBM TDB	
_	0	(Partitional of the partition of the par	USPĀT;	2003/10/28 09:45
		single adj substrate and mmic.ti,ab,clm.	US-PGPUB; EPO; JPO;	
			DERWENT; IBM_TDB	
-	0	single adj substrate and (monolithic	USPAT; US-PGPUB;	2003/10/28 09:46
		mmic).ti,ab,clm.	EPO; JPO; DERWENT;	
-	0	(plurality multiple) adj "chips" near6	IBM_TDB USPAT;	2003/10/28 09:46
		single adj substrate and (monolithic microwave millimeter adj wave	US-PGPUB; EPO; JPO;	
		mmic).ti,ab,clm.	DERWENT; IBM TDB	
-	29	"chips" near6 single adj substrate and (monolithic microwave millimeter adj wave	USPAT; US-PGPUB;	2003/10/28 09:46
		mmic).ti,ab,clm.	EPO; JPO; DERWENT;	
_	19	"chips" near3 single adj substrate and	IBM_TDB USPAT;	2003/10/28 10:20
		(monolithic microwave millimeter adj wave mmic).ti,ab,clm.	US-PGPUB; EPO; JPO;	2000,10,20 10.20
		manacy, capacing	DERWENT; IBM TDB	
-	0	"chips" near3 single adj substrate near6	USPAT;	2003/10/28 09:56
		ceramic and (monolithic microwave millimeter adj wave mmic).ti,ab,clm.	US-PGPUB; EPO; JPO;	
			DERWENT; IBM TDB	

			<u>,</u> -	
_	0	"chips" near3 single adj substrate near6	USPAT;	2003/10/28 09:56
		(transfer adj tape ceramic) and	US-PGPUB;	
		(monolithic microwave millimeter adj wave	EPO; JPO;	
		mmic).ti,ab,clm.	DERWENT;	
1			IBM_TDB	
-	47	"chips" near3 ceramic adj substrate and	USPAT;	2003/10/28 10:28
		(monolithic microwave millimeter adj wave	US-PGPUB;	
		mmic).ti,ab,clm.	EPO; JPO;	
ļ			DERWENT;	
			IBM TDB	
_	0	plurality near2 mmic near2 chips near6	USPĀT;	2003/10/28 10:29
		substrate adj board	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	l 0	plurality near2 (mmic chips) near6	USPAT;	2003/10/28 10:42
		substrate adj board	US-PGPUB;	
			EPO; JPO;	
	İ		DERWENT;	
			IBM TDB	ļ
_	13	(mmic "chips") near6 substrate adj board	USPAT;	2003/10/28 10:45
		and ceramic	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	۾	"chips" near6 substrate adj board and	USPAT;	2003/10/28 10:53
	Ĭ	ceramic and (mmic monlithic adj microwave)	US-PGPUB;	2003, 10, 20 10.03
		Ceramic and (maire monificate adj microwave)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	8	"chips" near6 substrate adj board and	USPAT;	2003/10/28 10:54
-		ceramic and (mmic monolithic adj	US-PGPUB;	2003/10/20 10.34
		microwave)	EPO; JPO;	
		microwave)	DERWENT;	
			IBM TDB	
l _	301	(333/247).CCLS.	USPAT	2003/10/28 10:54
 _	28		USPAT	2003/10/28 10:54
	20	substrate and mmic	JULKI	2003/10/20 10.55
1_	25	((333/247).CCLS.) and ceramic near5	USPAT	2003/10/28 11:28
-	25	substrate and mmic and chip	OSFAI	2003/10/26 11:26
	1	_	USPAT	2003/10/28 11:29
	0	("5852391").PN. (("5852391").PN.) and capacitor and	USPAT	2003/10/28 11:29
-		resistor	OSERI	2003/10/28 11:29
_	1		USPAT	2003/10/28 14:35
_	0	(("5852391").PN.) and capacitor		2003/10/28 14:35
-		,, , , , , , , , , , , , , , , , , , , ,	USPAT	2003/10/20 14:35
[_		(resistor resistance)	HGDVW	2003/10/20 15:06
_	1 1 1	("5982250").PN.	USPAT	2003/10/28 15:06
-	1 1	("5852391").PN.	USPAT	2003/10/28 16:09
	<u> </u>	("6175287").PN.	USPAT	2003/10/28 16:09

-	60	(US-6421012-\$ or US-6266015-\$ or	USPAT;	2003/10/28 17:12
		US-5331123-\$ or US-6580931-\$ or	US-PGPUB;	
		US-6552696-\$ or US-6492952-\$ or	DERWENT	
		US-6215454-\$ or US-6211824-\$ or		
		US-6195047-\$ or US-6498551-\$ or US-6522868-\$ or US-6507110-\$ or		
		US-6489679-\$ or US-6476463-\$ or		
		US-6442374-\$ or US-6072991-\$ or		
	+	US-6002375-\$ or US-5852391-\$ or		
		US-6627992-\$ or US-6594479-\$ or		
}		US-5111199-\$ or US-5422783-\$ or		
		US-5451818-\$ or US-5319329-\$ or		
		US-5239685-\$ or US-5406122-\$).did. or		
		(US-6175287-\$ or US-6278337-\$ or		
		US-6278159-\$ or US-6268779-\$ or		
		US-6424074-\$ or US-5545924-\$ or		
		US-6257058-\$ or US-6201728-\$ or	ļ	
		US-6124636-\$ or US-5898909-\$ or		
		US-5423080-\$ or US-6124765-\$ or		
		US-6073484-\$ or US-6441449-\$).did. or		
		(US-20030117245-\$ or US-20030155651-\$ or		
		US-20030148739-\$ or US-20020171141-\$ or		
		US-20030034861-\$ or US-20030027530-\$ or		
	1	US-20020132589-\$ or US-20030169134-\$ or		
1		US-20020030269-\$ or US-20020086655-\$ or		
		US-20010001224-\$ or US-20020055349-\$ or		į
		US-20020030250-\$).did. or (US-5451818-\$ or		
		US-5239685-\$ or WO-200223674-\$ or		
		EP-712534-\$ or JP-11214578-\$ or		
	2.2	EP-504020-\$ or WO-200075762-\$).did.	HCD3.	0000/10/00 17:00
-	11		USPAT;	2003/10/28 17:22
		US-5331123-\$ or US-6580931-\$ or	US-PGPUB; DERWENT	
		US-6552696-\$ or US-6492952-\$ or	DERWENT	
		US-6215454-\$ or US-6211824-\$ or US-6195047-\$ or US-6498551-\$ or		
		US-6522868-\$ or US-6507110-\$ or		
		US-6489679-\$ or US-6476463-\$ or		
		US-6442374-\$ or US-6072991-\$ or		
		US-6002375-\$ or US-5852391-\$ or		
		US-6627992-\$ or US-6594479-\$ or		
		US-5111199-\$ or US-5422783-\$ or		
		US-5451818-\$ or US-5319329-\$ or	 	
		US-5239685-\$ or US-5406122-\$).did. or		·
		(US-6175287-\$ or US-6278337-\$ or		
		US-6278159-\$ or US-6268779-\$ or		
		US-6424074-\$ or US-5545924-\$ or		
	•	US-6257058-\$ or US-6201728-\$ or		
		US-6124636-\$ or US-5898909-\$ or		
		US-5423080-\$ or US-6124765-\$ or		
		US-6073484-\$ or US-6441449-\$).did. or		
	[i	(US-20030117245-\$ or US-20030155651-\$ or		
		US-20030148739-\$ or US-20020171141-\$ or		
		US-20030034861-\$ or US-20030027530-\$ or		
]	US-20020132589-\$ or US-20030169134-\$ or		
	[US-20020030269-\$ or US-20020086655-\$ or US-20010001224-\$ or US-20020055349-\$ or		
		US-20010001224-\$ of US-20020055349-\$ of US-20020030250-\$).did. or (US-5451818-\$ or		
]	US-5239685-\$ or WO-200223674-\$ or		
		EP-712534-\$ or JP-11214578-\$ or		
		EP-504020-\$ or WO-200075762-\$).did.) and		
		(transfer adj tape lttt)		
_	6	(transfer adj tape lttt) near6 ltcc	USPAT;	2003/10/28 18:15
		,	US-PGPUB;	
			DERWENT	
	0	transfer adj tape adj lamination.ti,ab.	USPAT;	2003/10/28 18:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

_	0	transfer adj tape adj lamination and low	USPAT;	2003/10/28 18:16
	İ	adj temperature adj2 ceramic	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	14	transfer adj tape and low adj temperature	USPAT;	2003/10/28 18:24
		adj2 ceramic	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	
_	1	("4645552").PN.	USPAT	2003/10/28 18:46
_	l ī	("4453142").PN.	USPAT	2003/10/28 19:02
_	1	, , , , , , , , , , , , , , , , , , ,	USPAT	2003/10/28 19:02
_	2	, , , , , , , , , , , , , , , , , , , ,	USPAT	2003/10/29 09:00
_	l - 0	("jp-5063346\$-\$.did.").PN.	USPAT;	2003/10/29 18:16
		, JP Good of frame / class	US-PGPUB	
_	0	("jp-5063346\$-\$.did.").PN.	USPAT;	2003/10/29 18:17
		()p 00000104 4.0220. / 1210.	US-PGPUB;	
			JPO]
_	0	("jp-5063346\$-\$.did.").PN.	USPAT;	2003/10/29 18:17
	ľ	()p 30035404 4.a.a. /	US-PGPUB;	2003, 10, 23 10.1.
			JPO;	
			DERWENT	
	2	in_050633466¢ did	USPAT;	2003/10/29 18:21
_		jp-05063346\$-\$.did.	JPO;	2003/10/29 10:21
		4- 051000106 6 444	DERWENT	2003/10/29 18:18
_	2	jp-05199019\$-\$.did.	USPAT;	2003/10/29 18:18
			JPO;	
			DERWENT	2002/10/20 10:22
_	1	jp-61174693\$-\$.did.	USPAT;	2003/10/29 18:22
			JPO;	
			DERWENT	0000/10/00 10 00
_	2	jp-54135654\$-\$.did.	USPAT;	2003/10/29 18:22
			JPO;	
			DERWENT	0004/00/01 10 00
_	2	("5982250").PN.	USPAT;	2004/02/21 19:39
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0001/00/01 10 51
-	3	863030.ap.	USPAT;	2004/02/21 19:51
			US-PGPUB;	
	}		EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
–	2219		USPAT;	2004/02/21 19:52
		(455/73) or (333/26) or (333/247)).CCLS.	US-PGPUB	
–	0	(((257/277) or (257/664) or (257/728) or	USPAT;	2004/02/21 19:54
		(455/73) or (333/26) or (333/247)).CCLS.)	US-PGPUB;	
		and transceiver.ti,ab,clm. and (low adj	EPO; JPO;	
		temperature adj co-fired adj ceramic	DERWENT;	
		ltcc).ti,ab,clm.	IBM_TDB	
-	4	transceiver.ti,ab,clm. and (low adj	USPAT;	2004/02/21 19:55
		temperature adj co-fired adj ceramic	US-PGPUB;	
		ltcc).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	transceiver.ti,ab,clm. and (low adj	USPAT;	2004/02/21 20:45
		temperature adj co-fired adj ceramic	US-PGPUB;	
		ltcc).ti,ab,clm. and (multi-layer multi	EPO; JPO;	
		adj layer multilayer)	DERWENT;	
			IBM_TDB	
-	1	transceiver.ti,ab,clm. and (low adj	USPAT;	2004/02/21 20:46
		temperature adj co-fired adj ceramic	US-PGPUB;	
		ltcc).ti,ab,clm. and (multi-layer multi	EPO; JPO;	
		adj layer multilayer) and ground and (mm	DERWENT;	
		millimeter)	IBM_TDB	